

## **Power MOSFET**

# 60 V, 295 mA, Dual N-Channel with ESD Protection, SC-88

#### **Features**

- Low R<sub>DS(on)</sub>
- Low Gate Threshold
- Low Input Capacitance
- ESD Protected Gate
- This is a Pb-Free Device

#### **Applications**

- Low Side Load Switch
- DC-DC Converters (Buck and Boost Circuits)

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise stated)

Parameter			Symbol	Value	Units	
Drain-to-Source Voltage			$V_{DSS}$	60	V	
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V	
Continuous Drain	Steady	T <sub>A</sub> = 25°C	I <sub>D</sub>	295	mA	
Current (Note 1)	State	T <sub>A</sub> = 85°C		212		
	t≤5s	T <sub>A</sub> = 25°C		304		
		T <sub>A</sub> = 85°C		219		
Power Dissipation (Note 1)	Steady State	T <sub>A</sub> = 25°C	P <sub>D</sub>	250	mW	
	t ≤ 5 s			266		
Pulsed Drain Current	t <sub>p</sub> =	= 10 μs	I <sub>DM</sub>	900	mA	
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C	
Source Current (Body Diode)			I <sub>S</sub>	210	mA	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C	
Gate-Source ESD Rating (HBM, Method 3015)			ESD	1400	V	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Units
Junction-to-Ambient - Steady State	$R_{\theta JA}$	500	°C/W
Junction-to-Ambient – t ≤ 5 s	$R_{\theta JA}$	470	

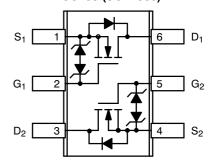
<sup>1.</sup> Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).

## NTJD5121N

#### http://onsemi.com

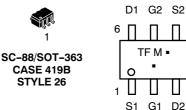
V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> Max
60 V	1.6 Ω @ 10 V	295 mA
	2.5 Ω @ 4.5 V	293 IIIA

#### SC-88 (SOT-363)



Top View

# MARKING DIAGRAM & PIN ASSIGNMENT



TF = Device Code

M = Date Code

Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTJD5121NT1G	SC-88 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.



### **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise stated)

# **NTJD5121N**

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS			•			•	•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 250 μA, ref to 25°C			92		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V,$ $V_{DS} = 60 V$	T <sub>J</sub> = 25°C			1.0	μΑ
		V <sub>DS</sub> = 60 V	T <sub>J</sub> = 125°C			500	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$				±10	μΑ
ON CHARACTERISTICS (Note 2)					-		-
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D}$	, = 250 μΑ	1.0	1.7	2.5	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				4.0		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 500 mA			1.0	1.6	Ω
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 200 mA			1.2	2.5	
Forward Transconductance	9FS	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 200 mA			80		S
CHARGES AND CAPACITANCES			•		•	•	•
Input Capacitance	C <sub>ISS</sub>	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 20 \text{ V}$			26		pF
Output Capacitance	C <sub>OSS</sub>				4.4		
Reverse Transfer Capacitance	C <sub>RSS</sub>				2.5		
Total Gate Charge	Q <sub>G(TOT)</sub>				0.9		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 4.5 V, V	ne = 25 V.		0.2		┦
Gate-to-Source Charge	Q <sub>GS</sub>	$I_{D} = 200 \text{ mA}$			0.3		
Gate-to-Drain Charge	Q <sub>GD</sub>				0.28		
SWITCHING CHARACTERISTICS (No	ote 3)		•		•	•	•
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{GS}$ = 45 V, $V_{DD}$ = 25 V, $I_{D}$ = 200 mA, $R_{G}$ = 25 $\Omega$			22		ns
Rise Time	t <sub>r</sub>				34		
Turn-Off Delay Time	t <sub>d(off)</sub>				34		
Fall Time	t <sub>f</sub>				32		
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C		0.8	1.2	V
		$I_S = 200 \text{ mA}$	T <sub>J</sub> = 85°C		0.7		1

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.